

BB02-YP :- 1.0mm X 1.0mm (0.039" X 0.039") SMD PIN HEADER, DUAL ROW, R/A - 04 TO 30 CONTACTS

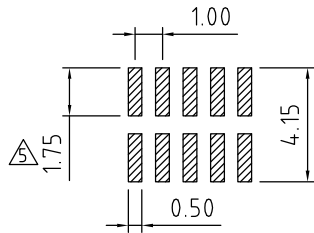
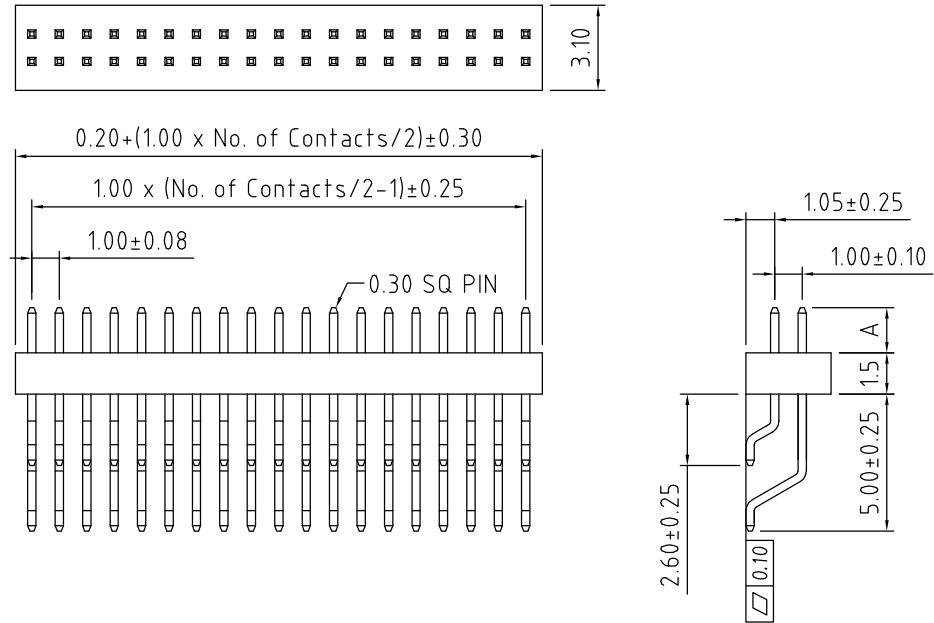
SPECIFICATIONS

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
CONTACTS RESISTANCE	20 m OHMS MAX.
DIELECTRIC WITHSTANDING	AC 300V
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0 STANDARD: LCP
PLATING	GOLD, TIN, OR SELECTIVE OVER MIN. 30U" NICKEL
SOLDERABILITY	IR REFLOW: 280°C FOR 10 SEC MANUAL SOLDER: 380°C FOR 3-5 SEC

NOTES:

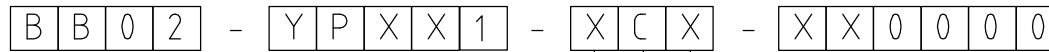
1. THE PACKAGING FOR 04 TO 08 CONTACTS IS BOX INSTEAD OF TUBE.

MATES WITH :- BB02-WA



RECOMMENDED PC BOARD SMD LAYOUT
(TOLERANCE: ±0.05)

HOW TO ORDER



NO. OF CONTACTS:
04 TO 30

CONTACT PLATING OPTIONS:
K = GOLD FLASH (STANDARD)
T = BRIGHT TIN
M = MATT TIN

INSULATOR THICKNESS=1.5MM

PACKAGING OPTIONS:
3 - TUBE (SEE NOTE.1)
6 - T & R
7 - T & R + FILM

PIN LENGTH 'A' (1/10mm)
PLEASE SPECIFY PIN LENGTH REQUIRED IN mm
I.E. 2.5mm = 25
STANDARD = 15
TOL. ±0.25mm

REV.	DATE & DRN
10	03/07/09 - CHC RELEASE
11	14/07/09 - NYM
12	03/08/10 - NYM
13	03/08/10 - NYM
14	03/08/10 - NYM
15	27/09/11 - NYM
16	13/03/12 - NYM
17	13/03/12 - NYM
18	13/03/12 - NYM
19	13/03/12 - NYM
20	13/03/12 - NYM

Scale: 5:1	THIRD ANGLE	Unstated Tolerances: X ± 0.30 X ± 0.25 XX ± 0.15 XXX ± 0.10	Material SEE NOTE
Drawn: CHC			NOT TO SCALE
App'd: XXX	Title: PIN HEADER		UNIT: mm
Date: 11 JAN. '13	Revision: 15		



Type: BB02-YP
BB02-YP
Drawing Number:
Sheet 1 of 1
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